

# FCP190N60E / FCPF190N60E

## N-Channel SuperFET® II MOSFET

600 V, 20.6 A, 190 mΩ

### Features

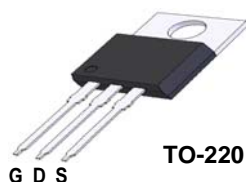
- 650 V @  $T_J = 150^\circ\text{C}$
- Max.  $R_{DS(on)} = 190\text{ m}\Omega$
- Ultra Low Gate Charge (Typ.  $Q_g = 63\text{ nC}$ )
- Low Effective Output Capacitance (Typ.  $C_{oss,eff} = 178\text{ pF}$ )
- 100% Avalanche Tested

### Applications

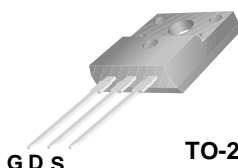
- LCD / LED / PDP TV Lighting
- Solar Inverter
- AC-DC Power Supply

### Description

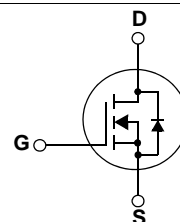
SuperFET®II MOSFET is Fairchild Semiconductor®'s first generation of high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. Consequently, SuperFETII MOSFET is suitable for various AC/DC power conversion for system miniaturization and higher efficiency.



TO-220



TO-220F



### MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	FCP190N60E	FCPF190N60E	Unit
$V_{DSS}$	Drain to Source Voltage	600		V
$V_{GSS}$	Gate to Source Voltage	- DC	$\pm 20$	V
		- AC (f > 1 Hz)	$\pm 30$	V
$I_D$	Drain Current	- Continuous ( $T_C = 25^\circ\text{C}$ )	20.6	A
		- Continuous ( $T_C = 100^\circ\text{C}$ )	13.1	
$I_{DM}$	Drain Current	- Pulsed (Note 1)	61.8	A
$E_{AS}$	Single Pulsed Avalanche Energy	(Note 2)	400	mJ
$I_{AR}$	Avalanche Current	(Note 1)	4.0	A
$E_{AR}$	Repetitive Avalanche Energy	(Note 1)	2.1	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	20	V/ns
	MOSFET dv/dt		100	
$P_D$	Power Dissipation	( $T_C = 25^\circ\text{C}$ )	208	W
		- Derate above $25^\circ\text{C}$	1.67	W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150		$^\circ\text{C}$
$T_L$	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300		$^\circ\text{C}$

\*Drain current limited by maximum junction temperature

### Thermal Characteristics

Symbol	Parameter	FCP190N60E	FCPF190N60E	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.6	3.2	$^\circ\text{C/W}$
$R_{\theta CS}$	Thermal Resistance, Case to Heat Sink (Typical)	0.5	0.5	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62.5	62.5	

## Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FCP190N60E	FCP190N60E	TO-220	-	-	50
FCPF190N60E	FCPF190N60E	TO-220F	-	-	50

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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### Off Characteristics

$BV_{DSS}$	Drain to Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 10\text{ mA}, T_J = 25^\circ\text{C}$	600	-	-	V
		$V_{GS} = 0\text{ V}, I_D = 10\text{ mA}, T_J = 150^\circ\text{C}$	650	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 10\text{ mA}$ , Referenced to $25^\circ\text{C}$	-	0.67	-	V/ $^\circ\text{C}$
$BV_{DS}$	Drain-Source Avalanche Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 20\text{ A}$	-	700	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 480\text{ V}, V_{GS} = 0\text{ V}$	-	-	1	$\mu\text{A}$
		$V_{DS} = 480\text{ V}, T_C = 125^\circ\text{C}$	-	-	10	
$I_{GSS}$	Gate to Body Leakage Current	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$	-	-	$\pm 100$	$\mu\text{A}$

### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\text{ }\mu\text{A}$	2.5	-	3.5	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{ V}, I_D = 10\text{ A}$	-	0.16	0.19	$\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 20\text{ V}, I_D = 10\text{ A}$	-	20	-	S

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V}$ $f = 1\text{ MHz}$	-	2385	3175	pF
$C_{oss}$	Output Capacitance		-	1795	2396	pF
$C_{rss}$	Reverse Transfer Capacitance		-	110	165	pF
$C_{oss}$	Output Capacitance	$V_{DS} = 380\text{ V}, V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}$	-	42	-	pF
$C_{oss\text{ eff.}}$	Effective Output Capacitance	$V_{DS} = 0\text{ V to } 480\text{ V}, V_{GS} = 0\text{ V}$	-	178	-	pF
$Q_{g(tot)}$	Total Gate Charge at 10V	$V_{DS} = 380\text{ V}, I_D = 10\text{ A}$ $V_{GS} = 10\text{ V}$ (Note 4)	-	63	82	nC
$Q_{gs}$	Gate to Source Gate Charge		-	10	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge		-	24	-	nC
ESR	Equivalent Series Resistance	$f = 1\text{ MHz}$	-	5	-	$\Omega$

### Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 380\text{ V}, I_D = 10\text{ A}$ $V_{GS} = 10\text{ V}, R_G = 4.7\text{ }\Omega$ (Note 4)	-	23	56	ns
$t_r$	Turn-On Rise Time		-	14	38	ns
$t_{d(off)}$	Turn-Off Delay Time		-	101	212	ns
$t_f$	Turn-Off Fall Time		-	15	40	ns

### Drain-Source Diode Characteristics

I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	20.2	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	60.6	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 10 A	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 10 A	-	308	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> /dt = 100 A/μs	-	4.8	-	μC

#### Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2.  $I_{AS} = 4\text{ A}, V_{DD} = 50\text{ V}, R_G = 25\text{ }\Omega$ , Starting  $T_J = 25^\circ\text{C}$
3.  $I_{SD} \leq 10\text{ A}, di/dt \leq 200\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ\text{C}$
4. Essentially Independent of Operating Temperature Typical Characteristics

## Typical Performance Characteristics

Figure 1. On-Region Characteristics

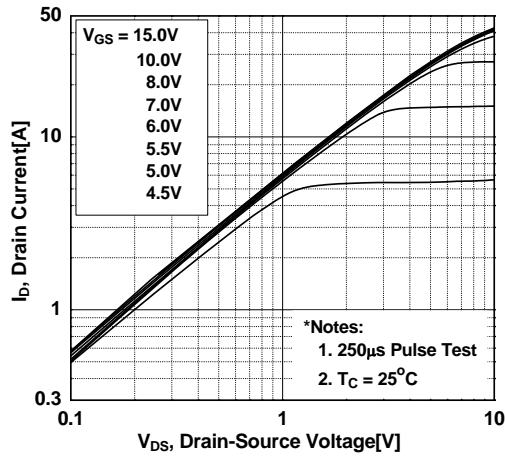


Figure 2. Transfer Characteristics

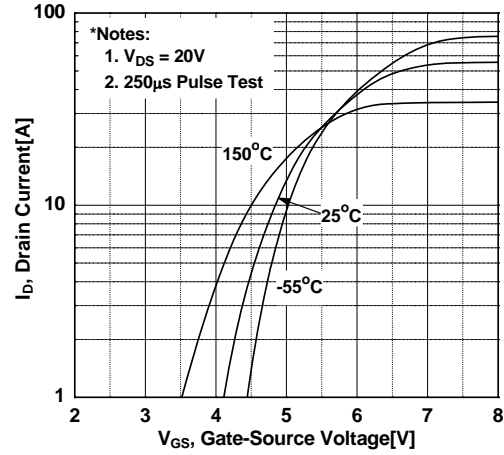


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

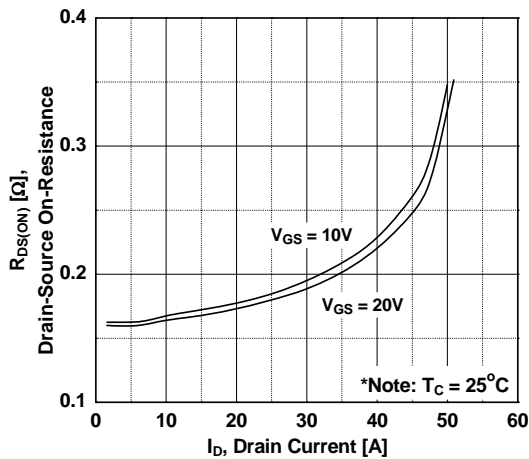


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

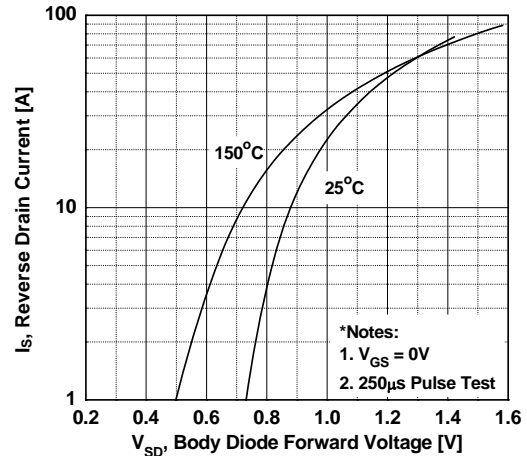


Figure 5. Capacitance Characteristics

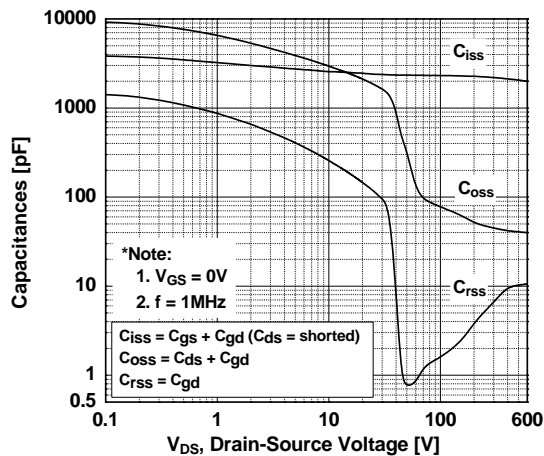
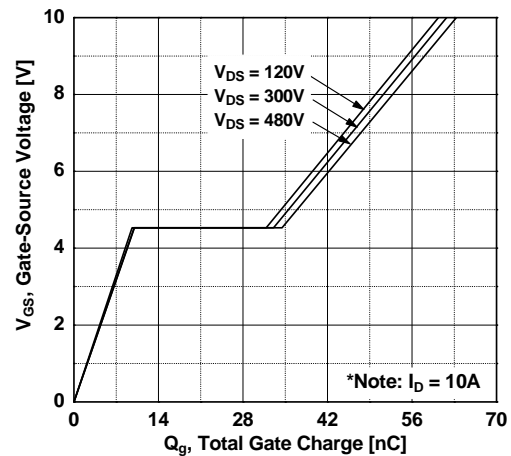


Figure 6. Gate Charge Characteristics



## Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

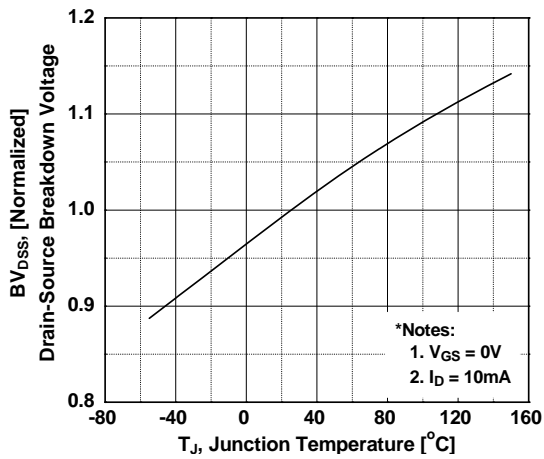


Figure 8. On-Resistance Variation vs. Temperature

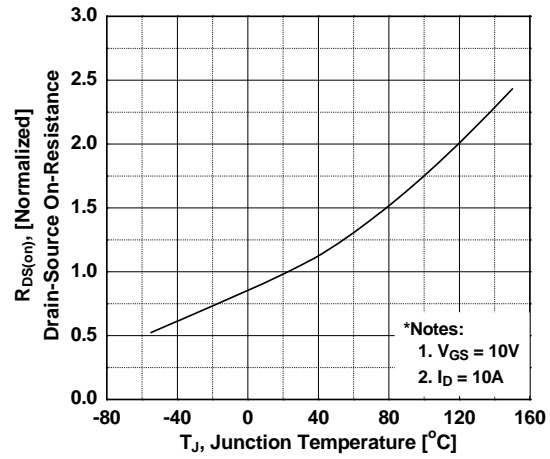


Figure 9. Maximum Safe Operating Area vs. Case Temperature - FCP190N60E

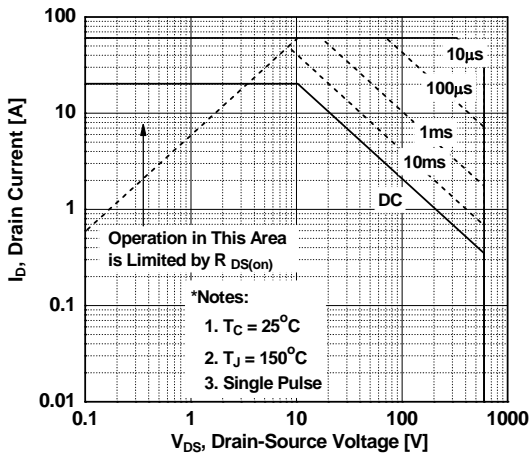


Figure 10. Maximum Safe Operating Area vs. Case Temperature - FCPF190N60E

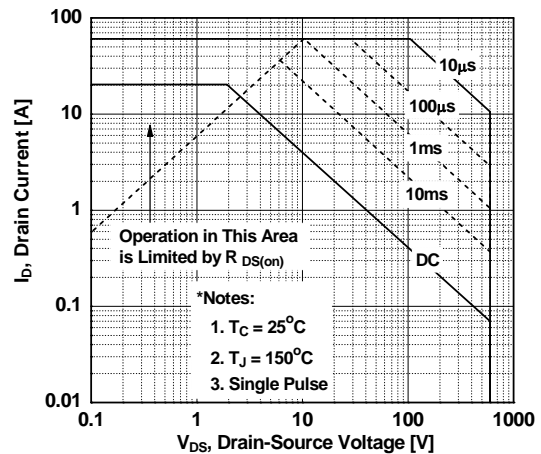


Figure 11. Maximum Drain Current

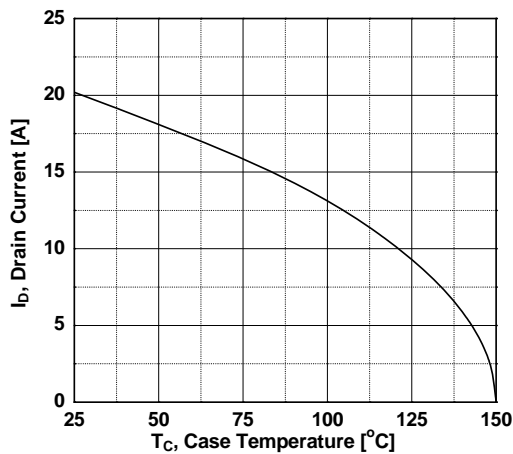
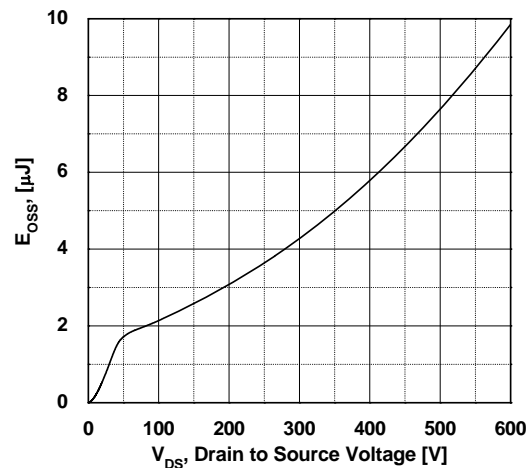


Figure 12. E\_oss vs. Drain to Source Voltage Switching Capability



## Typical Performance Characteristics (Continued)

Figure 13. Transient Thermal Response Curve - FCP190N60E

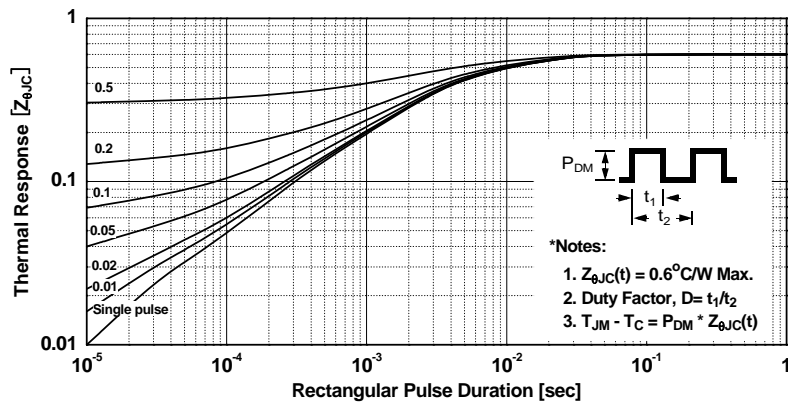
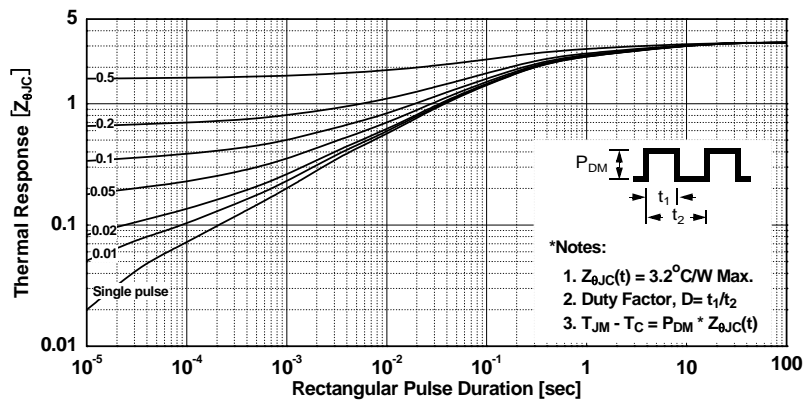
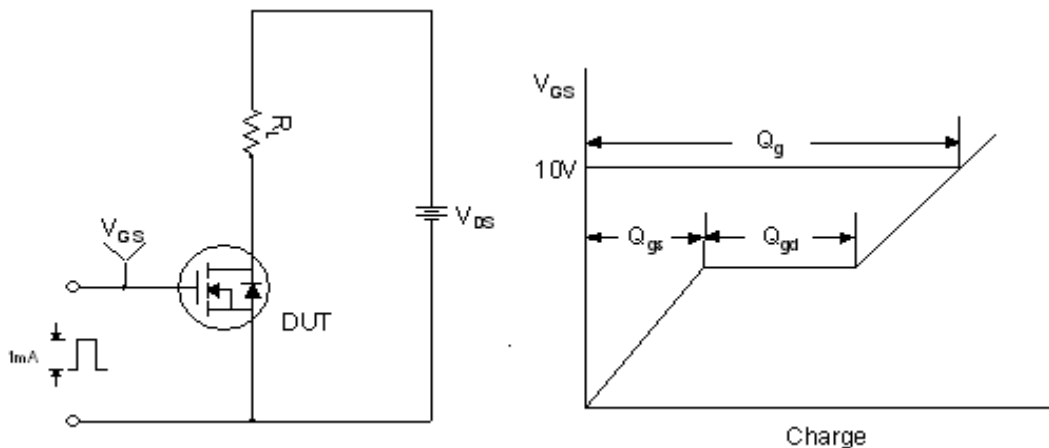


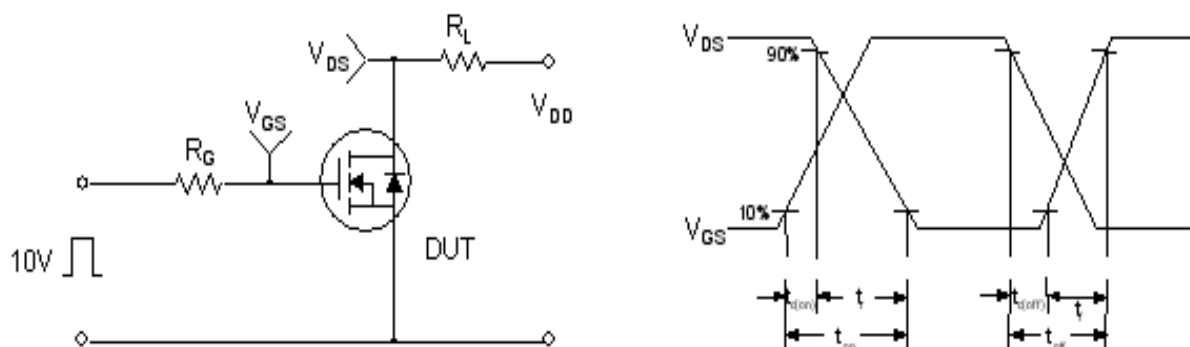
Figure 14. Transient Thermal Response Curve - FCPF190N60E



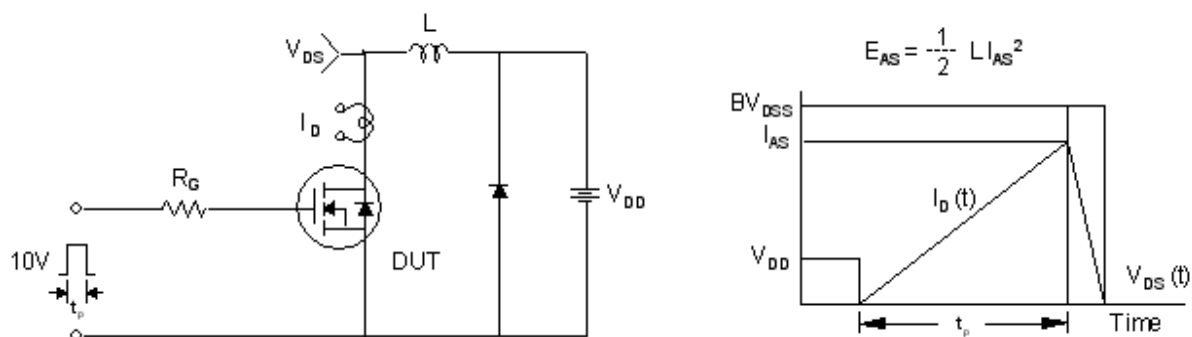
Gate Charge Test Circuit & Waveform



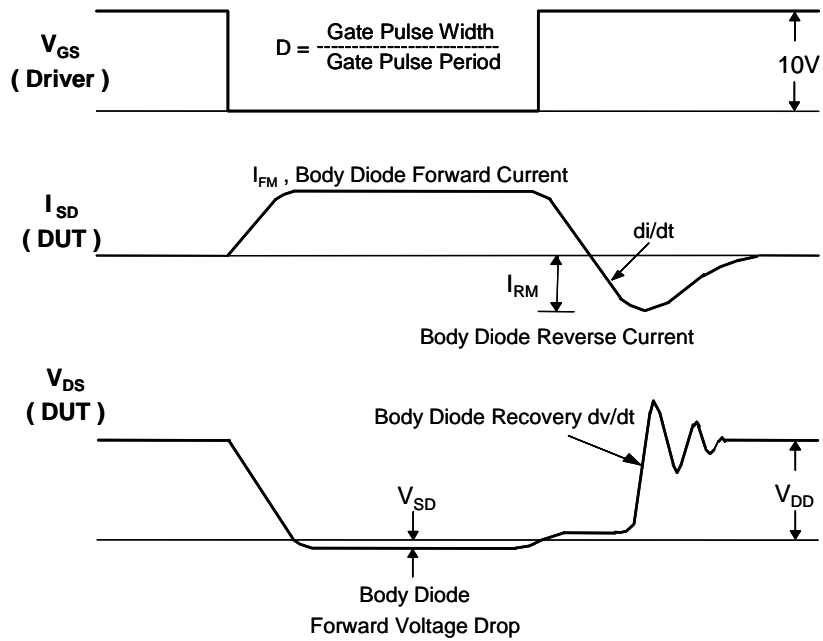
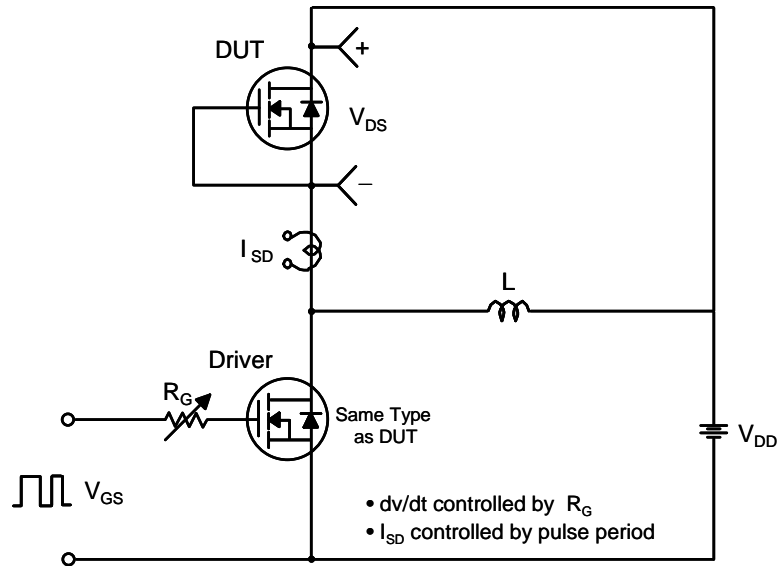
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

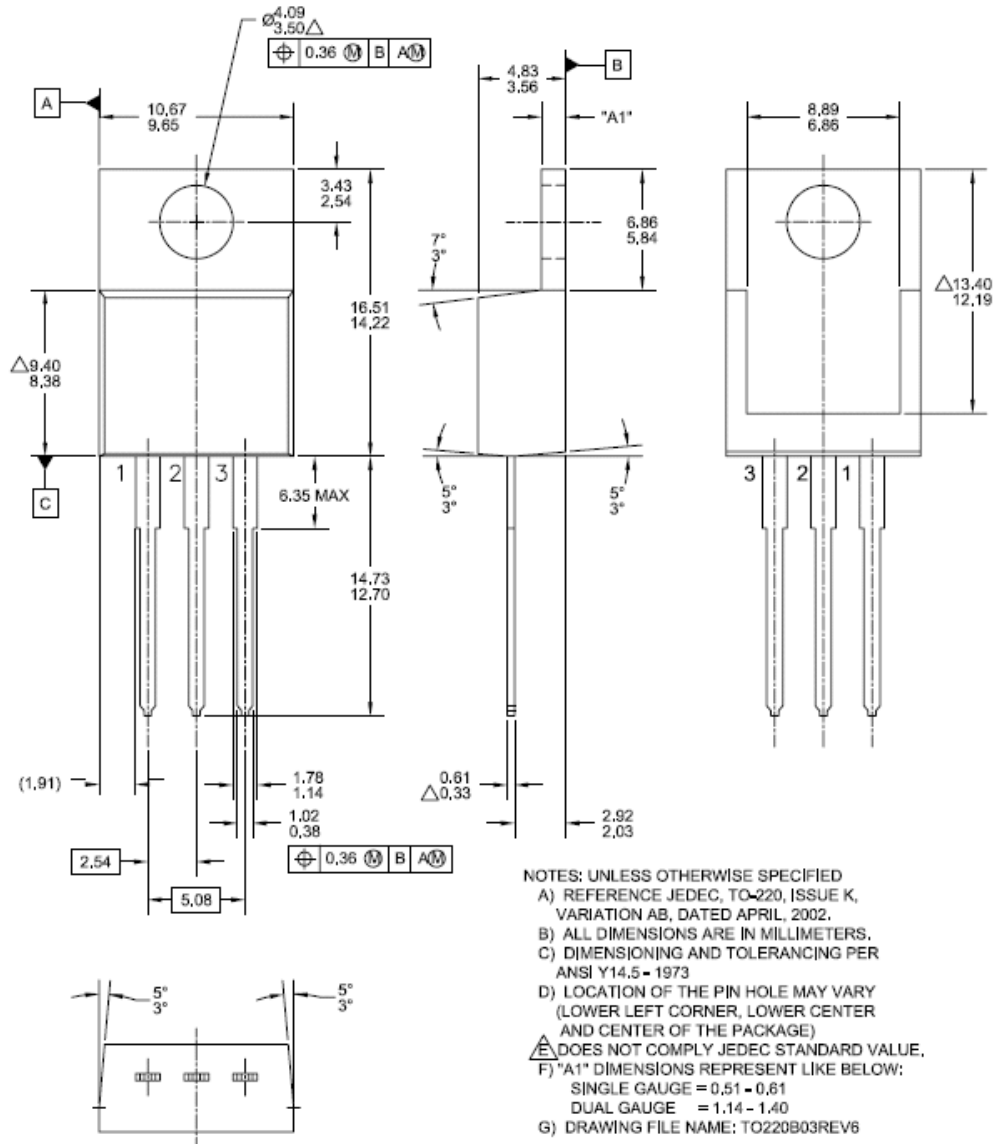


# Peak Diode Recovery dv/dt Test Circuit & Waveforms



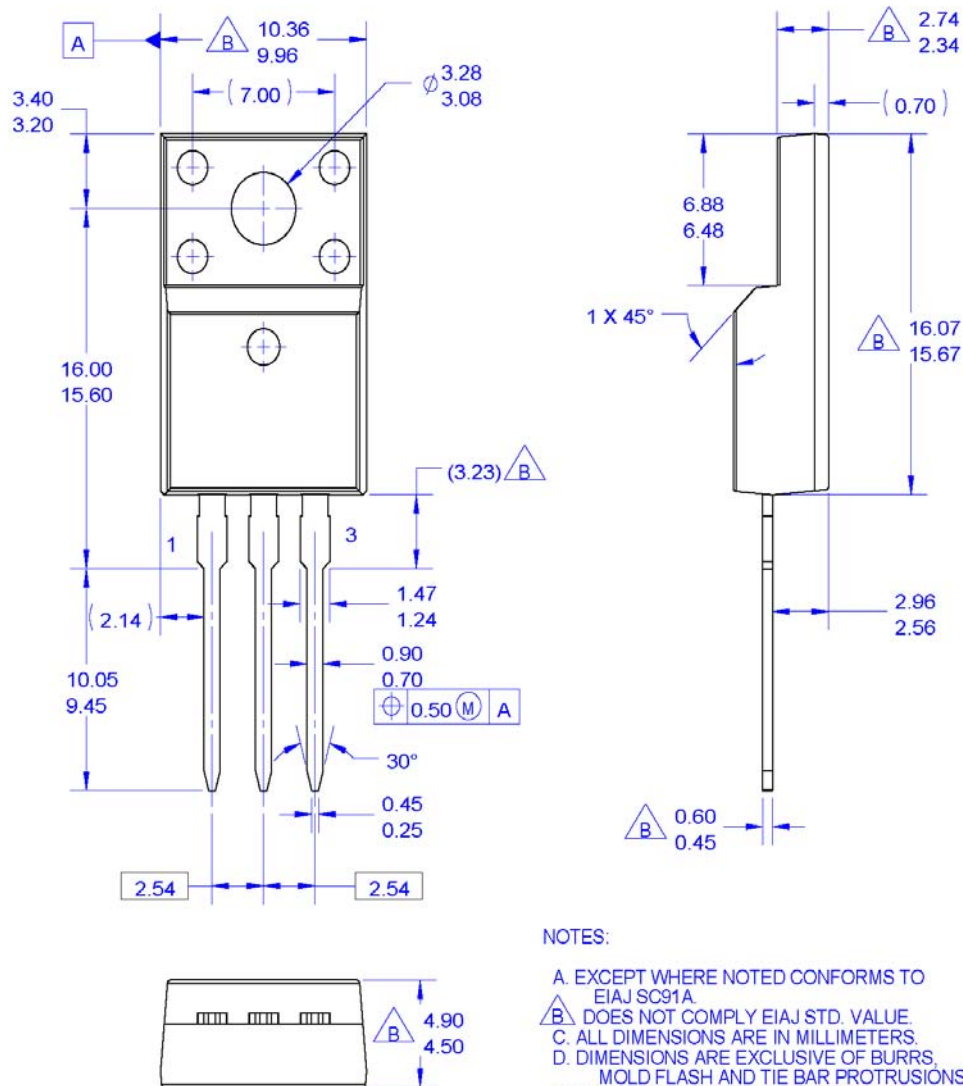
## Mechanical Dimensions

## TO-220AB



## Package Dimensions

## TO-220F (Retractable)



## NOTES:

- A. EXCEPT WHERE NOTED CONFORMS TO EIAJ SC91A.
- B. DOES NOT COMPLY EIAJ STD. VALUE.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- E. DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994.
- F. DRAWING FILE NAME: TO220M03REV3

\* Front/Back Side Isolation Voltage : AC 2500V

Dimensions in Millimeters



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CTL™	GTO™	TM	TinyPWM™
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Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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